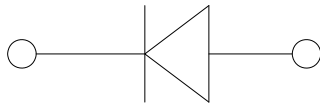


Low profile package  
Ideal for automated placement  
Glass passivated chip junction  
High forward surge capability  
Meets MSL level 1, per J-STD-020, LF maximum peak of 260 °C

For use in general purpose rectification of power supplies, inverters, converters, and freewheeling diodes for consumer and telecommunication.



: DO-214AC (SMA)

Molding compound meets UL 94 V-0 flammability rating, RoHS-compliant, halogen-free

: Tin plated leads, solderable per

J-STD-002 and JESD22-B102

Cathode line denotes the cathode end

( $T_a=25$  Unless otherwise specified)

Parameter	Symbol	Unit	Value
Device marking code			GS1R
Maximum Repetitive Peak Reverse Voltage	VRRM	V	1300
Maximum RMS Voltage	VRMS	V	910
Maximum DC blocking Voltage	VDC	V	1300
Average rectified output current @60Hz sine wave, resistance load, TL (Fig.1)	IO	A	1.0
Forward Surge Current (Non-repetitive) @60Hz Half-sine wave, 1 cycle, $T_j=25$	IFSM	A	30
Forward Surge Current (Non-repetitive) @1ms, square wave, 1 cycle, $T_j=25$			60
Current squared time @1ms t 8.3ms $T_j=25$	I <sup>2</sup> t	A <sup>2</sup> s	3.735
Storage temperature	Tstg		-55 ~ +150
Junction temperature	Tj		-55 ~ +150

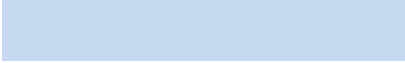
$T_a=25$  Unless otherwise specified

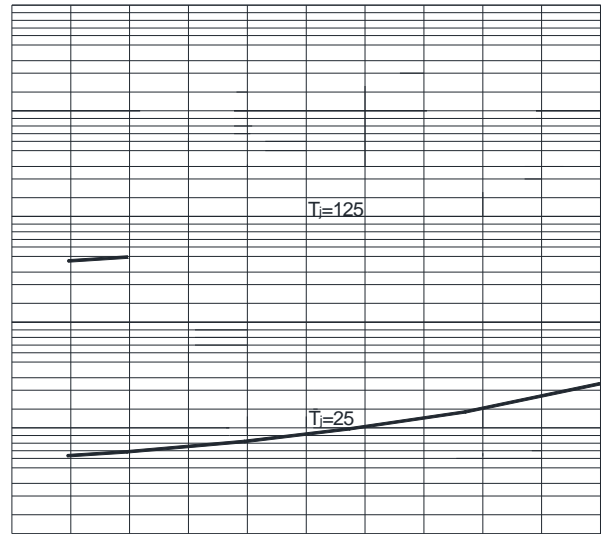
Parameter	Symbol	Unit	Value
Maximum instantaneous forward voltage	VF	V	IFM=1.0A 1.0
Maximum DC reverse current at rated DC blocking voltage	IR	μA	$T_j=25$ 5
			$T_j=125$ 50
Typical junction capacitance	Cj	pF	Measured at 1MHz and Applied Reverse Voltage of 4.0 V.D.C 15



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T<sub>a</sub>=25 Unless otherwise specified





Dim	Min	Max
A	1.25	1.58
B	2.40	2.83
C	4.00	4.75
D	1.90	2.30
E	4.93	5.28
F	0.76	1.41
G	0.05	0.20
H	0.15	0.31
I	1.70	2.10

Dim	Millimeters
P1	4.00
P2	1.50
P3	6.50
Q1	2.50
Q2	1.70



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The information presented in this document is for reference onl